



Material Content Data Sheet



Sales Product Name		TLF51801ELV		Issued		2. August 2018		
MA#		MA001033070						
Package		PG-SSOP-14-3		Weight*		83.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.743	2.10	2.10	20997	20997
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8301	
wire	non noble metal	copper	7440-50-8	27.978	33.71	34.59	337057	345877
	noble metal	gold	7440-57-5	0.210	0.25	0.25	2536	2536
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1204
encapsulation	plastics	epoxy resin	-	4.596	5.54		55369	
	inorganic material	silicondioxide	60676-86-0	45.260	54.53	60.19	545261	601834
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11760	11760
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9248	9248
glue	plastics	epoxy resin	-	0.161	0.19		1937	
	noble metal	silver	7440-22-4	0.482	0.58	0.77	5811	7748
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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